BGA Heat Sink - High Performance maxiFLOW/superGRIP





ATS Part#: ATS-X50230P-C1-R0

Description: 23.00 x 23.00 x 17.50 mm BGA Heat Sink - High

Performance maxiFLOW/superGRIP

Heat Sink Type: maxiFLOW
Heat Sink Attachment: superGRIP

Equivalent Part Number: N/A

*Image above is for illustration purpose only.

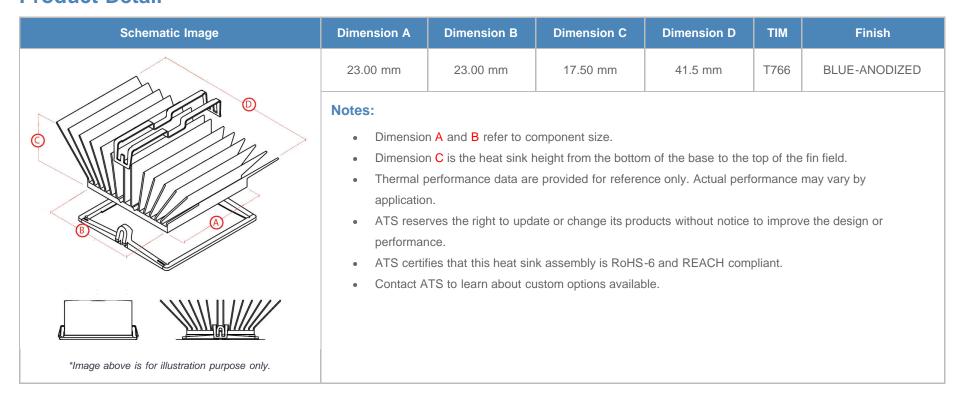
Features & Benefits

- Designed for 23 x 23 mm components
- Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	5.1 °C/W	4.2 °C/W	3.6 °C/W	3.3 °C/W	3 °C/W	2.8 °C/W	2.6 °C/W
	Ducted Flow	4.1	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail







Mouser Electronics

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